

INSTALLATION AND OPERATION

USER MANUAL

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UM680A

Automotive Grade GNSS High Precision RTK Positioning Module

Revision History

Version	Revision History	Date
R1.0	First release	Oct. 2024
R1.1	Updated 3.5 Recommended Footprint on the PCB. Updated 4.3 Stencil. Updated Figure 3-1 UM680A Recommended Minimal Design and added C4 in the remarks.	Mar. 2025
R2.0	Updated the typical value of C in Table 2-4 Dimensions and added a note about the module's shield.	Apr. 2025

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Foreword

This document describes the information of the hardware, package, specification and the use of Unicore UM680A module.

Target Readers

This document applies to technicians who are familiar with GNSS receivers.



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1 Introduction

UM680A is an automotive-grade GNSS navigation and positioning module designed for intelligent driving field. It is based on the multi-system, dual-frequency and high-performance GNSS SoC - UC6580A, which conforms to the requirements of AEC-Q100, and the manufacturing process is in line with IATF 16949.

UM680A supports GPS/BeiDou/GLONASS*/Galileo/QZSS/NavIC* L1+L5 frequencies, providing centimeter-level RTK positioning. It has two sub-models, UM680A-12 and UM680A-13, of which UM680A-13 supports up to 105 °C. See **Table 1-1** for more information.



Figure 1-1 UM680A High Precision Positioning Module

^{*} Only supported by specific firmware.



1.1 Key Specifications

Table 1-1 Technical Specifications

	UM680A-12	UM680A-13	
Products	Multi-system dual-frequency high	Multi-system dual-frequency high	
	precision RTK positioning module	precision RTK positioning module	
Illustration	UMG80A PIN:231041400001X SN:B421480001	UNICUTE UM680A Pinicastid-4000000XX SinicB4214800001	
Dimension	22.0 mm × 17.0 mm × 2.65 mm	22.0 mm × 17.0 mm × 2.65 mm	
Package	54 pin LGA	54 pin LGA	
Working Temperature	-40 °C to +85 °C	-40 °C to +105 °C	
Storage Temperature	-40 °C to +85 °C	-40 °C to +105 °C	
RF Input			
	GPS: L1C/A+L5	GPS: L1C/A+L5	
	BDS: B1I+B1C*+B2a	BDS: B1I+B1C*+B2a	
	Galileo: E1+E5a	Galileo: E1+E5a	
Frequency	GLONASS: G1*	GLONASS: G1*	
	NavIC: L5*	NavIC: L5*	
	QZSS: L1+L5	QZSS: L1+L5	
	SBAS	SBAS	
VSWR	≤ 2.5	≤ 2.5	
Input Impedance	50 Ω	50 Ω	
Antenna Gain	15 dB to 30 dB	15 dB to 30 dB	
Interface			
UART ¹	×2	×2	
I ² C ²		•	

^{*} Supported by specific firmware.

¹ TTL; baud rate: 115200 to 921600 bps.

² Reserved; address: 7 bit; working mode: slave; supports up to 400 Kbps.

	UM680A-12	UM680A-13	
Products	Multi-system dual-frequency high precision RTK positioning module	Multi-system dual-frequency high precision RTK positioning module	
SPI ³	•	•	
PPS	×1	×1	
EVENT	×1	×1	
RESET_N	•	•	
RTK_STAT	•	•	
GNSS Antenna	×1	×1	
Performance			
	Cold start: 26 s	Cold start: 26 s	
TTFF	Hot start: 2 s	Hot start: 2 s	
	Reacquisition: 2 s	Reacquisition: 2 s	
Single Point	Horizontal: 1.5 m (open sky)	Horizontal: 1.5 m (open sky)	
Positioning Accuracy (RMS)	Vertical: 2.5 m (open sky)	Vertical: 2.5 m (open sky)	
RTK Horizontal:		Horizontal:	
Positioning	1 cm + 1ppm (open sky)	1 cm + 1ppm (open sky)	
Accuracy (RMS)	Vertical:	Vertical:	
(HIVIS)	2 cm + 1ppm (open sky)	2 cm + 1ppm (open sky)	
Velocity Accuracy (RMS) ⁴	0.05 m/s	0.05 m/s	
	Tracking: -162 dbm	Tracking: -162 dbm	
Completivites	Cold start: -147 dbm	Cold start: -147 dbm	
Sensitivity	Hot start: -157 dbm	Hot start: -157 dbm	
	Reacquisition: -158 dbm	Reacquisition: -158 dbm	
Data Update Rate	1 Hz/5 Hz/10 Hz	1 Hz/5 Hz/10 Hz	
1PPS Accuracy (RMS)	20 ns	20 ns	

 $^{^3}$ Reserved; alternate function of Pin 42 to 45; working mode: slave; supports up to 4 Mbps.

⁴ 68% at 30 m/s for dynamic operation, open sky



Products	UM680A-12 Multi-system dual-frequency high precision RTK positioning module	UM680A-13 Multi-system dual-frequency high precision RTK positioning module			
Data Format	NMEA 0183 Unicore Protocol	NMEA 0183 Unicore Protocol			
	RTCM	RTCM			
Electrical Specifications					
Voltage	2.7 V to 3.6 V, Typ.: 3.3 V	2.7 V to 3.6 V, Typ.: 3.3 V			
LNA Feed Power	2.7 V to 3.3 V, <100 mA	2.7 V to 3.3 V, <100 mA			
Power Consumption	240 mW	240 mW			
Environmental Specifications					
Humidity	95% No condensation	95% No condensation			
Vibration	GB/T 28046.3; ISO 16750.3	GB/T 28046.3; ISO 16750.3			
Shock	GB/T 28046.3; ISO 16750.3	GB/T 28046.3; ISO 16750.3			

1.2 Block Diagram

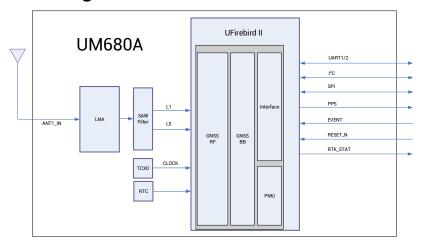


Figure 1-2 UM680A Block Diagram

1. RF Part

The receiver gets filtered and enhanced GNSS signals from the antenna via a coaxial cable. The RF part converts the RF input signals into the IF signals, and converts IF analog signals into digital signals required for UFirebird II chip.

2. UFirebird II SoC (UC6580A)

UFirebird II is the new generation RF-baseband and high-precision algorithm integrated GNSS SoC developed by Unicore. It adopts 22 nm technology and low power

consumption design, supporting multi-path mitigation, anti-jamming and high precision GNSS joint positioning. The chip is especially suitable for the application scenarios which are sensitive to power and size.

3. Interfaces

UM680A has interfaces such as UART, I²C*, SPI*, PPS, EVENT, RTK_STAT and RESET_N.

There are two UARTs. UART1 is the master serial port, supporting data transmission and firmware upgrade, and the I/O signal type is LVTTL. The baud rate can be configured by users. UART2 is a backup port and only supports data transmission; it cannot be used for firmware upgrade.

^{*} I²C and SPI are reserved interfaces.



2 Hardware

2.1 Pin Definition

See Figure 2-1 for the definition of UM680A-12/UM680A-13.

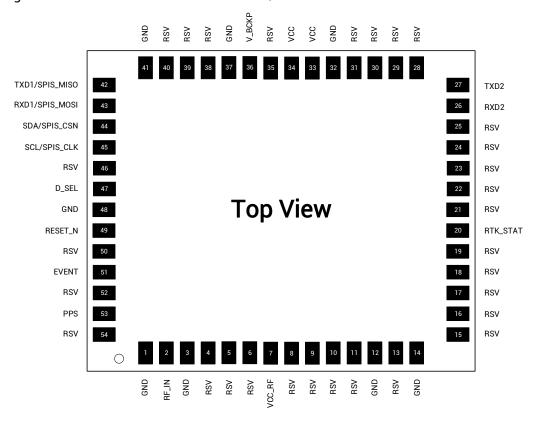


Figure 2-1 UM680A-12/UM680A-13 Pin Definition

Table 2-1 UM680A-12/UM680A-13 Pin Definition

No.	Pin	I/O	Description
1	GND	_	Ground
2	RF_IN	I	GNSS antenna signal input
3	GND	_	Ground
4	RSV	_	Reserved; leave floating
5	RSV	_	Reserved; leave floating
6	RSV	_	Reserved; leave floating
7	VCC_RF ⁵	0	Antenna feed output

⁵ Not recommended to use VCC_RF to feed the antenna (VCC_RF has not been optimized for antilightning strike and anti-surge due to the compact size of the module).

No.	Pin	I/O	Description
8	RSV	_	Reserved; leave floating
9	RSV	_	Reserved; leave floating
10	RSV	_	Reserved; leave floating
11	RSV	_	Reserved; leave floating
12	GND	_	Ground
13	RSV	_	Reserved; leave floating
14	GND	_	Ground
15	RSV	_	Reserved; leave floating
16	RSV	_	Reserved; leave floating
17	RSV	_	Reserved; leave floating
18	RSV	_	Reserved; leave floating
19	RSV	_	Reserved; leave floating
20	RTK_STAT	0	RTK positioning indicator: active high; outputs high for RTK fixed solution, and low for other status.
21	RSV	_	Reserved; leave floating
22	RSV	_	Reserved; leave floating
23	RSV	_	Reserved; leave floating
24	RSV	_	Reserved; leave floating
25	RSV	_	Reserved; leave floating
26	RXD2	I	UART2 input, LVTTL level
27	TXD2	0	UART2 output, LVTTL level
28	RSV	_	Reserved; leave floating
29	RSV	_	Reserved; leave floating
30	RSV	_	Reserved; leave floating
31	RSV	_	Reserved; leave floating
32	GND	_	Ground
33	VCC	I	Power supply (+3.3 V)
34	VCC	I	Power supply (+3.3 V)
35	RSV	_	Reserved; leave floating



When the main power supply VCC is cut off, V_BCKP supplies power to RTC and relevant register. Supply voltage: 2.0 V to 3.6 V, and the working current is less than 10 µA at 25 °C. If you do not use the hot start function, connect V_BCKP to VCC or a standalone power source. Do NOT connect it to ground or leave it floating. 37 GND — Ground 38 RSV — Reserved; leave floating 39 RSV — Reserved; leave floating 40 RSV — Reserved; leave floating 41 GND — Ground 42 TXD1/SPIS_MISO O Master In/Slave Out of SPI slave (D_SEL=GND) 43 RXD1/SPIS_MOSI I Master Out/Slave In of SPI slave (D_SEL=GND) 44 SDA/SPIS_CSN I SPI slave clock (D_SEL=VCC or floating); SPI slave clock (D_SEL=GND) 45 SCL/SPIS_CLK I SPI slave clock (D_SEL=COC or floating); SPI slave clock (D_SEL=GND) 46 RSV — Reserved; leave floating 47 D_SEL I Use pin 42 to 45 as a SPI slave when D_SEL = GND, as UART1 and I²C When D_SEL=VCC or floating 48 GND — Ground 49 RESET_N I System reset; active low; the active time should be no less than 5 ms 50 RSV — Reserved; leave floating 51 EVENT I Event mark input with adjustable frequency and polarity 52 RSV — Reserved; leave floating 53 PPS O Pulse per second with adjustable pulse width and polarity 54 RSV — Reserved; leave floating	No.	Pin	I/O	Description
Reserved; leave floating RSV	36	V_BCKP	I	V_BCKP supplies power to RTC and relevant register. Supply voltage: 2.0 V to 3.6 V, and the working current is less than 10 µA at 25 °C. If you do not use the hot start function, connect V_BCKP to VCC or a standalone power source. Do NOT connect it to ground
RSV — Reserved; leave floating 40 RSV — Reserved; leave floating 41 GND — Ground UART1 output (D_SEL=VCC or floating); 42 TXD1/SPIS_MISO O Master In/Slave Out of SPI slave (D_SEL=GND) 43 RXD1/SPIS_MOSI I WASTER OUT/Slave In of SPI slave (D_SEL=GND) 44 SDA/SPIS_CSN I SPI slave chip select (D_SEL=GND) 45 SCL/SPIS_CLK I SPI slave clock (D_SEL=GND) 46 RSV — Reserved; leave floating 47 D_SEL I SEL I Select pin; Use pin 42 to 45 as a SPI slave when D_SEL = GND, as UART1 and I2C When D_SEL=VCC or floating 48 GND — Ground 49 RESET_N I System reset; active low; the active time should be no less than 5 ms 50 RSV — Reserved; leave floating 51 EVENT I Event mark input with adjustable frequency and polarity 52 RSV — Reserved; leave floating Pulse per second with adjustable pulse width and polarity	37	GND	_	Ground
40 RSV — Reserved; leave floating 41 GND — Ground UART1 output (D_SEL=VCC or floating); Master In/Slave Out of SPI slave (D_SEL=GND) UART1 input (D_SEL=VCC or floating); Master Out/Slave In of SPI slave (D_SEL=GND) 43 RXD1/SPIS_MOSI I Master Out/Slave In of SPI slave (D_SEL=GND) 44 SDA/SPIS_CSN I SPI slave chip select (D_SEL=GND) 45 SCL/SPIS_CLK I SPI slave chip select (D_SEL=GND) 46 RSV — Reserved; leave floating Interface select pin; Use pin 42 to 45 as a SPI slave when D_SEL = GND, as UART1 and I ² C When D_SEL=VCC or floating 48 GND — Ground 49 RESET_N I System reset; active low; the active time should be no less than 5 ms 50 RSV — Reserved; leave floating 51 EVENT I Event mark input with adjustable frequency and polarity 52 RSV — Reserved; leave floating Pulse per second with adjustable pulse width and polarity	38	RSV	_	Reserved; leave floating
41 GND — Ground UART1 output (D_SEL=VCC or floating); Master In/Slave Out of SPI slave (D_SEL=GND) UART1 input (D_SEL=VCC or floating); Master Out/Slave In of SPI slave (D_SEL=GND) 43 RXD1/SPIS_MOSI I Master Out/Slave In of SPI slave (D_SEL=GND) 44 SDA/SPIS_CSN I I²C data (D_SEL=VCC or floating); SPI slave chip select (D_SEL=GND) 45 SCL/SPIS_CLK I I²C clock (D_SEL=VCC or floating); SPI slave clock (D_SEL=GND) 46 RSV — Reserved; leave floating Interface select pin; Use pin 42 to 45 as a SPI slave when D_SEL = GND, as UART1 and I²C When D_SEL=VCC or floating 48 GND — Ground 49 RESET_N I System reset; active low; the active time should be no less than 5 ms 50 RSV — Reserved; leave floating 51 EVENT I Event mark input with adjustable frequency and polarity 52 RSV — Reserved; leave floating 53 PPS O Pulse per second with adjustable pulse width and polarity	39	RSV	_	Reserved; leave floating
UART1 output (D_SEL=VCC or floating); Master In/Slave Out of SPI slave (D_SEL=GND) UART1 input (D_SEL=VCC or floating); Master Out/Slave In of SPI slave (D_SEL=GND) 43 RXD1/SPIS_MOSI I Master Out/Slave In of SPI slave (D_SEL=GND) 44 SDA/SPIS_CSN I SPI slave chip select (D_SEL=GND) 45 SCL/SPIS_CLK I SPI slave clock (D_SEL=VCC or floating); SPI slave clock (D_SEL=GND) 46 RSV — Reserved; leave floating Interface select pin; Use pin 42 to 45 as a SPI slave when D_SEL = GND, as UART1 and I²C When D_SEL=VCC or floating 48 GND — Ground 49 RESET_N I System reset; active low; the active time should be no less than 5 ms 50 RSV — Reserved; leave floating 51 EVENT I Event mark input with adjustable frequency and polarity 52 RSV — Reserved; leave floating 53 PPS O Pulse per second with adjustable pulse width and polarity	40	RSV	_	Reserved; leave floating
42 TXD1/SPIS_MISO O Master In/Slave Out of SPI slave (D_SEL=GND) UART1 input (D_SEL=VCC or floating); Master Out/Slave In of SPI slave (D_SEL=GND) 44 SDA/SPIS_CSN I I ² C data (D_SEL=VCC or floating); SPI slave chip select (D_SEL=GND) 45 SCL/SPIS_CLK I I ² C clock (D_SEL=VCC or floating); SPI slave clock (D_SEL=GND) 46 RSV - Reserved; leave floating Interface select pin; Use pin 42 to 45 as a SPI slave when D_SEL = GND, as UART1 and I ² C When D_SEL=VCC or floating 48 GND - Ground 49 RESET_N I System reset; active low; the active time should be no less than 5 ms 50 RSV - Reserved; leave floating 51 EVENT I Event mark input with adjustable frequency and polarity 52 RSV - Reserved; leave floating Pulse per second with adjustable pulse width and polarity	41	GND	_	Ground
RXD1/SPIS_MOSI Master Out/Slave In of SPI slave (D_SEL=GND)	42	TXD1/SPIS_MISO	0	Master In/Slave Out of SPI slave
SPI slave chip select (D_SEL=GND) SCL/SPIS_CLK SPI slave chip select (D_SEL=GND) RESEL I	43	RXD1/SPIS_MOSI	I	Master Out/Slave In of SPI slave
SPI slave clock (D_SEL=GND) 46 RSV — Reserved; leave floating Interface select pin; Use pin 42 to 45 as a SPI slave when D_SEL = GND, as UART1 and I²C When D_SEL=VCC or floating 48 GND — Ground 49 RESET_N I System reset; active low; the active time should be no less than 5 ms 50 RSV — Reserved; leave floating 51 EVENT I Event mark input with adjustable frequency and polarity 52 RSV — Reserved; leave floating 53 PPS O Pulse per second with adjustable pulse width and polarity	44	SDA/SPIS_CSN	1	,
Interface select pin; Use pin 42 to 45 as a SPI slave when D_SEL = GND, as UART1 and I ² C When D_SEL=VCC or floating 48 GND — Ground 49 RESET_N I System reset; active low; the active time should be no less than 5 ms 50 RSV — Reserved; leave floating 51 EVENT I Event mark input with adjustable frequency and polarity 52 RSV — Reserved; leave floating 53 PPS O Pulse per second with adjustable pulse width and polarity	45	SCL/SPIS_CLK	1	,
47 D_SEL I Use pin 42 to 45 as a SPI slave when D_SEL = GND, as UART1 and I ² C When D_SEL=VCC or floating 48 GND — Ground 49 RESET_N I System reset; active low; the active time should be no less than 5 ms 50 RSV — Reserved; leave floating 51 EVENT I EVENT I EVENT I Reserved; leave floating 52 RSV PROMITY 53 PPS O Pulse per second with adjustable pulse width and polarity	46	RSV	_	Reserved; leave floating
49 RESET_N I System reset; active low; the active time should be no less than 5 ms 50 RSV — Reserved; leave floating 51 EVENT I Event mark input with adjustable frequency and polarity 52 RSV — Reserved; leave floating 53 PPS O Pulse per second with adjustable pulse width and polarity	47	D_SEL	I	Use pin 42 to 45 as a SPI slave when D_SEL = GND, as UART1 and I ² C When D_SEL=VCC
the active time should be no less than 5 ms RESET_N the active time should be no less than 5 ms Reserved; leave floating Event mark input with adjustable frequency and polarity Reserved; leave floating Pulse per second with adjustable pulse width and polarity	48	GND	_	Ground
Event mark input with adjustable frequency and polarity Reserved; leave floating Pulse per second with adjustable pulse width and polarity	49	RESET_N	I	-
51 EVENT 1 and polarity 52 RSV — Reserved; leave floating 53 PPS O Pulse per second with adjustable pulse width and polarity	50	RSV	_	Reserved; leave floating
Pulse per second with adjustable pulse width and polarity	51	EVENT	1	
and polarity	52	RSV	_	Reserved; leave floating
54 RSV – Reserved; leave floating	53	PPS	0	•
	54	RSV	<u> </u>	Reserved; leave floating

2.2 Electrical Specifications

2.2.1 Absolute Maximum Ratings

Table 2-2 Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit	Remark
Power Supply	VCC	-0.2	3.6	٧	
Backup Battery	V_BCKP	-0.2	3.6	V	
Digital Pin Voltage		-0.2	3.6	V	
Antenna RF Input Power	RF_IN	-	-3	dBm	
Storage Temperature	T _{STG}	-40	+85	°C	UM680A-12
Storage Temperature	T _{STG}	-40	+105	°C	UM680A-13
Reflow Soldering	т		+245	°C	
Temperature	T _{SLDR}	-	T245	U	

2.2.2 Operational Conditions

Table 2-3 Operational Conditions

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Power Supply	VCC	2.7	3.3	3.6	V	
VCC Ripple	Vp-p			50	mV	
Peak Current	Ісср			200	mA	VCC = 3.0 V
Average Tracking Current ⁶	I _{ACQ}	70	80	100	mA	VCC = 3.0 V
Low Level Input Voltage	V_{IL}	-0.3		0.2 × VCC	V	
High Level Input Voltage	V _{IH}	0.7 × VCC		3.6	V	
Low Level Output Voltage	V _{OL}	0		0.4	V	I _{out} = -2 mA
High Level Output Voltage	V _{OH}	VCC - 0.4		VCC	V	I _{out} = 2 mA
Antenna Gain	G _{ANT}	15	20	30	dB	

⁶ Since the product has capacitors inside, inrush current occurs during power-on. You should evaluate in the actual environment in order to check the effect of the supply voltage drop caused by inrush current in the system.

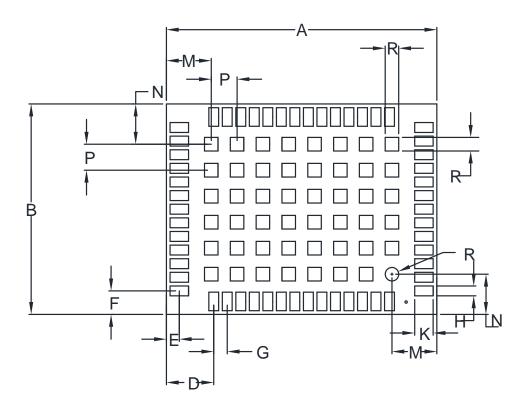


2.3 Dimensions

Table 2-4 Dimensions

Symbol	Min. (mm)	Typ. (mm)	Max. (mm)
Α	21.80	22.00	22.50
В	16.80	17.00	17.50
С	2.40	2.65	2.80
D	3.75	3.85	3.95
Е	0.95	1.05	1.15
F	1.80	1.90	2.00
G	1.00	1.10	1.20
Н	0.70	0.80	0.90
К	1.40	1.50	1.60
М	3.55	3.65	3.75
N	3.15	3.25	3.35
Р	2.00	2.10	2.20
R	1.00	1.10	1.20
X	0.72	0.82	0.92

Note: The module uses one-piece shield.



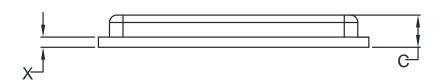


Figure 2-2 UM680A Mechanical Dimensions



3 Hardware Design

3.1 Recommended Minimal Design

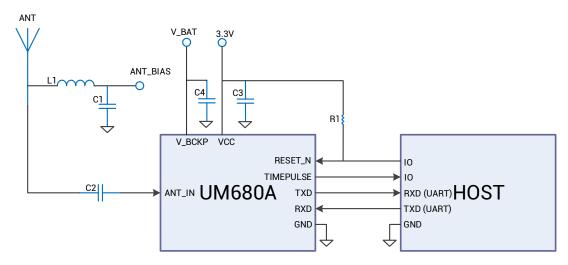


Figure 3-1 UM680A Recommended Minimal Design

Remarks:

- L1: 68 nH RF inductor in 0603 package is recommended
- C1: 100 nF + 100 pF capacitors connected in parallel is recommended
- C2: 100 pF capacitor is recommended
- C3: Several 10 µF + 100 nF capacitors connected in parallel is recommended
- C4: 100 nF capacitor is recommended
- R1: 10 kΩ resistor is recommended; pull up

3.2 Antenna Feed Design

UM680A supports feeding the antennal from the outside of the module rather than from the inside. It is recommended to use devices with high power and that can withstand high voltage. Gas discharge tube, varistor, TVS tube and other high-power protective devices may also be used in the power supply circuit to further protect the module from lightning strike and surge.

If the antenna feed supply ANT_BIAS and the module's main supply VCC use the same power rail, the ESD, surge and overvoltage from the antenna will have an effect on VCC, which may cause damage to the module. Therefore, it is recommended to design an independent power rail for the ANT_BIAS to reduce the possibility of module damage.

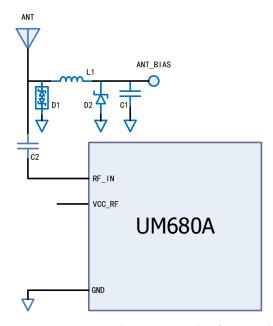


Figure 3-2 UM680A External Antenna Feed Reference Circuit

Remarks:

- L1: feed inductor, 68nH RF inductor in 0603 package is recommended;
- C1: decoupling capacitor, it is recommended to connect two capacitors of 100nF/100pF in parallel;
- C2: DC blocking capacitor, recommended 100pF capacitor;
- Not recommended to use VCC_RF as ANT_BIAS to feed the antenna (VCC_RF has not been optimized for the anti-lightning strike and anti-surge due to the compact size of the module)
- D1: ESD diode, choose the ESD protection device that supports high frequency signals (above 2000 MHz)
- D2: TVS diode, choose the TVS diode with appropriate clamping specification according to the requirement of feed voltage and antenna withstand voltage



3.3 Power-on and Power-off

VCC

- The VCC initial level when power-on should be less than 0.4 V.
- The VCC ramp when power-on should be monotonic, without plateaus.
- The voltages of undershoot and ringing should be within 5% VCC.
- VCC power-on waveform: The time interval from 10% rising to 90% must be within 100 µs to 10 ms.
- Power-on time interval: The time interval between the power-off (VCC < 0.4 V) to the next power-on must be larger than 500 ms.

V_BCKP

- The V_BCKP initial level when power-on should be less than 0.4 V.
- The V_BCKP ramp when power-on should be monotonic, without plateaus.
- The voltages of undershoot and ringing should be within 5% V_BCKP.
- V_BCKP power-on waveform: The time interval from 10% rising to 90% must be within 100 µs to 10 ms.
- Power-on time interval: The time interval between the power-off (V_BCKP < 0.4 V) to the next power-on must be larger than 500 ms.

3.4 Grounding and Heat Dissipation

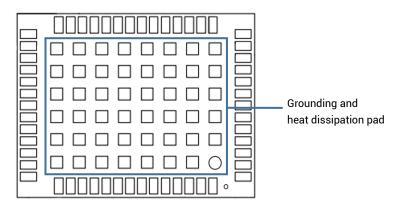


Figure 3-3 Grounding and Heat Dissipation Pad

The 48 pads in the rectangle in **Figure 3-3** are for grounding and heat dissipation. In the PCB design, it is recommended to connect them to a large sized ground to strengthen the heat dissipation.



3.5 Recommended Footprint on the PCB

The dimensions of UM680A's footprint on the PCB is recommended to be the same as that of the module's pads, as shown in **Figure 3-4 Recommended Footprint**. For more information about the module's dimensions, see **2.3 Dimensions**.

- For the convenience of hardware testing and debugging, proper test points can be added for the functional pins of the module.
- The dimensions of PCB pads can be optimized according to the specific production process to ensure manufacturability and reliability.

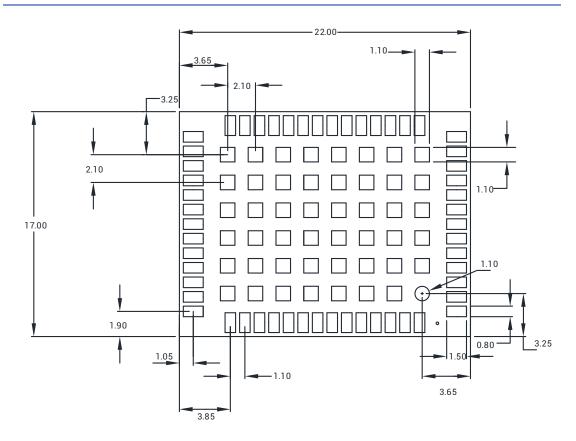


Figure 3-4 Recommended Footprint (Unit: mm)

4 Production Requirements

4.1 Clean



Do NOT use alcohol or other organic solvents to clean the module; otherwise it may lead to flux residues flooding into the shielding cover, causing mildew and other problems.

4.2 Soldering

Recommended soldering temperature curve is as follows:

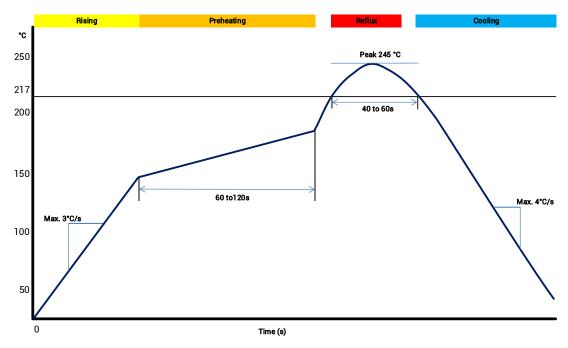


Figure 4-1 Soldering Temperature (Lead-free)

Temperature Rising Stage

Rising slope: Max. 3 °C/s

Rising temperature range: 50 °C to 150 °C

Preheating Stage

Preheating time: 60 s to 120 s

Preheating temperature range: 150 °C to 180 °C

Reflux Stage

Over melting temperature (217 °C) time: 40 s to 60 s

Peak temperature for soldering: no higher than 245 °C



Cooling Stage

Cooling slope: Max. 4 °C/s



In order to prevent falling off during soldering of the module, do not solder it on the back of the board during design, and better not go through soldering cycle twice.

The setting of soldering temperature depends on many factors of the factory, such as board type, solder paste type, solder paste thickness, etc. Please also refer to the relevant IPC standards and indicators of solder paste.

4.3 Stencil

The apertures in the stencil need to meet the customer's own design requirements and inspection specifications. The thickness of the stencil is recommended to be 0.15 mm (not less than 0.12 mm).

The design of the stencil can be optimized according to the specific production process to ensure manufacturability and reliability.

5 Packaging

5.1 Label Description



Figure 5-1 Label Description

5.2 Ordering Information

Product Model	Sub-model	Description	
UM680A	12	Automotive grade; dual-frequency RTK positioning module; operating temperature: -40 °C to +85 °C; supporting firmware upgrade; 22 mm x 17 mm; 250 pieces/reel	
	13	Automotive grade; dual-frequency RTK positioning module; operating temperature: -40 °C to +105 °C; supporting firmware upgrade; 22 mm x 17 mm; 250 pieces/reel	



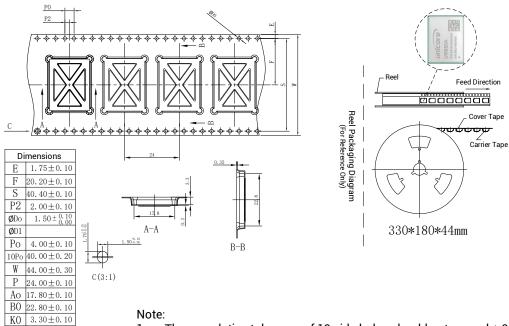
5.3 Product Packaging

The UM680A module uses carrier tape and reel (suitable for mainstream surface mount devices), packaged in vacuum-sealed aluminum foil antistatic bags, with a desiccant inside to prevent moisture. When using reflow soldering process to solder modules, please strictly comply with IPC standard to conduct humidity control. As packaging materials such as the carrier tape can only withstand the temperature of 55 °C, modules shall be removed from the package during baking.



Figure 5-2 UM680A Package

 0.35 ± 0.05



- 1. The cumulative tolerance of 10 side holes should not exceed \pm 0.2 mm.
- 2. Material of the tape: Black antistatic PS (surface impedance 10⁵-10¹¹) (surface static voltage <100 V), thickness: 0.35 mm.
- 3. Total length of the 13-inch reel package: 6.816 m (Length of the first part of empty packets: 0.408 m, length of packets containing modules: 6 m, length of the last part of empty packets: 0.408 m).
- 4. Total number of packets in the 13-inch reel package: 284 (Number of the first part of empty packets: 17; actual number of modules in the packets: 250; number of the last part of empty packets: 17).
- 5. All dimension designs are in accordance with EIA-481-C-2003.
- 6. The maximum bending degree of the carrier tape within the length of 250 mm should not exceed 1 mm (see the figure below).

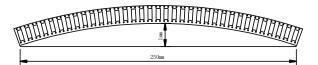


Figure 5-3 UM680A Reel Package Diagram



Table 5-1 Package Description

Item	Description
Module Number	250 pieces/reel
Reel Size	Tray: 13"
	External diameter: 330 ± 2 mm
	Internal diameter: 180 ± 2 mm
	Width: 44.5 ± 0.5 mm
	Thickness: 2.0 ± 0.2 mm
Carrier Tape	Space between (center-to-center distance): 24 mm

Before surface mounting, make sure that the color of the 30% circle on the HUMIDITY INDICATOR is blue (see Figure 5-4). If the color of the 20% circle is pink and the color of the 30% circle is lavender (see Figure 5-5), you must bake the module until it turns to blue. The UM680A is rated at MSL level 3. Refer to the relevant IPC/JEDEC J-STD-033 standards for the package and operation requirements. Users may access to the website www.jedec.org to get more information.

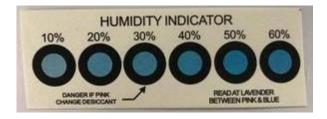


Figure 5-4 Normal Humidity Indication

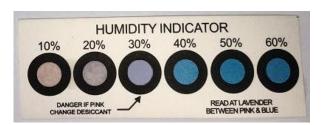


Figure 5-5 Abnormal Humidity Indication

The shelf life of the UM680A module packaged in vacuum-sealed aluminum foil antistatic bags is one year.

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